

### Product Description

Shin-Etsu's G-751 thermal interface grease is a general purpose product that exhibits superior thermal conductivity. G-751 is an excellent product for applications that require high thermal conductivity without the need for electrical insulation.

### Product Features

- Superior thermal conductivity
- Cold resistance
- Water repellency

### Typical Applications

- CPUs
- MPUs
- Semiconductor elements and heat sinks requiring high thermal conductivity

### Typical Properties

Type	Thermal Grease
One/Two Component	One
Low Molecular Weight Siloxane Stripped?	Y
Color	Gray
Density @ 23C (g/cm <sup>3</sup> )	2.51
Viscosity (Pa·s)	420
Volume Resistivity (TΩ·m)	0.008
Thermal Conductivity (W/m·K)	4.50
Thermal Resistance (mm <sup>2</sup> ·K/W)	17
% Oil Separation	0.01
% Volatile Content	0.10
Usable Temp. Range (C)	-50 to +120
Bond Line Thickness (µm)	62

*Note: Values are not for specification purposes.*

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